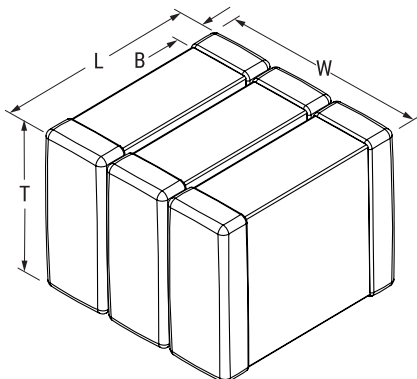


KONNEKT KC-Link, Ceramic, 0.45 uF, 10%, 650 VDC, COG, 3-Chip Low Loss Orientation.



Dimensions	
L	9.3mm +/-0.6mm
W	7.7mm +/-0.6mm
T	10.2mm +/-0.4mm
B	1.27mm +/-0.4mm

Packaging Specifications	
Weight:	3.3 g
Packaging:	T&R, 180mm
Packaging Quantity:	50

General Information	
Series:	KONNEKT KC-Link
Style:	KONNEKT
Description:	KC-LINK with KONNEKT, SMD, MLCC, Ultra-Stable, Class I
Features:	Ultra-Stable
RoHS:	Yes
Termination:	Tin
AEC-Q200:	No
Notes:	3-Chip Low Loss Orientation.
Chip Size:	3640
MSL:	1

Specifications	
Capacitance:	0.45 uF
Measurement Condition:	1 kHz 1.0Vrms
Capacitance Tolerance:	10%
Voltage DC:	650 VDC
Dielectric Withstanding Voltage:	845 VDC
Temperature Range:	-55/+150°C
Temperature Coefficient:	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor:	0.1% 1 kHz 1.0Vrms
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	2.222 GOhms

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